

# SOT1147-1

plastic thermal enhanced extremely thin small outline  
package; no leads; 16 terminals;UTLP based

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HXSON16U
<b>Package type industry code</b>	HXSON16U
<b>Package style descriptive code</b>	HXSON (thermal enhanced extremely thin small outline; no leads)
<b>Package style suffix code</b>	U (UTLP based)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	2-10-2009

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		[tbd]	-	[tbd]	3.1	mm
E	package width		[tbd]	-	[tbd]	1.2	mm
A	seated height		[tbd]	-	[tbd]	0.5	mm
e	nominal pitch		-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	16	-	



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2. Package outline

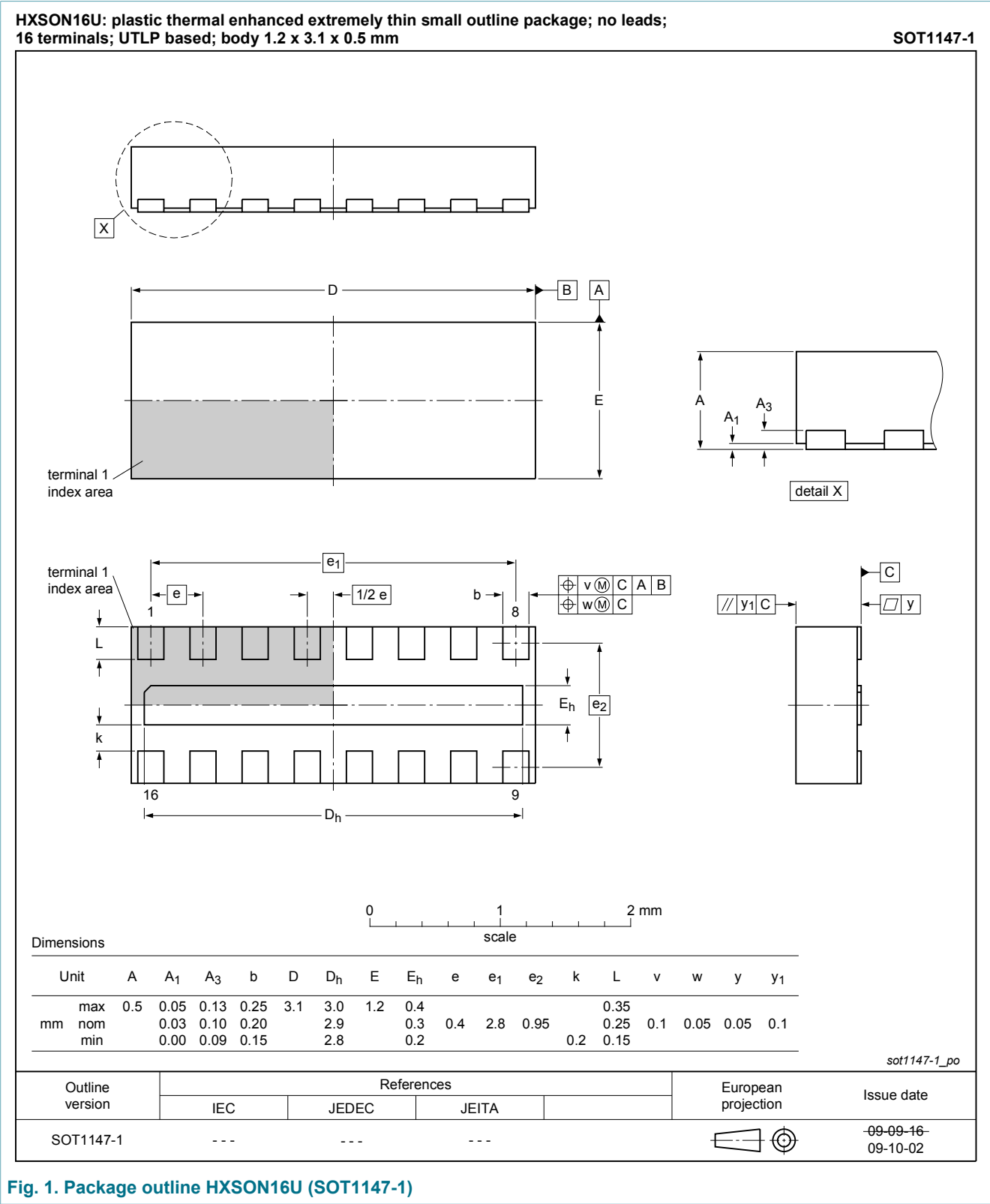


Fig. 1. Package outline HXSON16U (SOT1147-1)

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### 3. Legal information

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based

4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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